

Quarterly Progress Report:

Project Number and Title: 1.8: Enhancing Intelligent Compaction with Passive Wireless Sensors

Research Area: Thrust # 1, Monitoring and Assessment for Enhanced Life

PI: Ehsan Ghazanfari, The University of Vermont **Co-PI(s):** Hamid Ossareh, The University of Vermont

Reporting Period: 7/1/2020 to 9/30/2020

Submission Date: 9/30/2020

Overview:

During the past quarter, we continued to analyze data from two projects: (1) the data (IC, pavement quality indicators (PQI), and nuclear gauge density (NGD)) that we collected from field tests in Route 117 (Vermont) reclaimed asphalt pavement project, and (2) the data collected from another RSB project in Vermont. The focus of data analysis was to: (i) assess the reliability of IC measurement values (ICMVs), and (ii) potential utilization of ICMVs as a function of vibration amplitude and frequency in the control system, with the goal of optimizing the compaction process, and minimizing the spatial variability of the ICMVs. Furthermore, we made some progress in fine tuning the viable options for design/ruggedization of the pressure sensors to survive the extreme pressure and temperature during compaction process. The performed work in previous months helps us move closer toward the next steps of the project and to improve the IC performance and facilitate the process of geomaterial compaction and pavement performance monitoring.

Table 1: Task Progress					
Task Number	Start Date	End Date	% Complete		
Task 1: IC in sub- base/asphalt	07/01/2018	08/30/2020	85%		
Task 2: Passive sensor	06/01/2019	02/30/2021	65%		
Task 3: Integration options/performance eval.	03/01/2021	06/30/2021	15%		
Overall Project:	07/01/2019	06/30/2021	60%		

Table 2: Budget Progress					
Project Budget Spend – Project to Date % Project to Date*					
\$254,732	\$158,284	60.2%			

Table 3: Presentations at Conferences, Workshops, Seminars, and Other Events					
Title	Event	Type	Location	Date(s)	
Presentation title	Name of event (i.e. TIDC 1 st Annual	i.e. Conference, Symposium,			
Investigating methods to enhance intelligent compaction performance	VTrans Research and Innovation Symposium	Seminar, Symposium	Virtual	9/9/2020	

Table 4: Publications and Submitted Papers and Reports							
Type Title Citation Date Status							
The revised version of the submitted conference paper (4th International Conference on Transportation							
Geotechnics), reported in previous quarterly report, is under review.							

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Participants and Collaborators:

Table 5: Active Principal Investigators, faculty, administrators, and Management Team Members					
Individual Name	Email Address	Department	Role in Research		
		Civil &	Principal Investigator		
Ehsan Ghazanfari	Ehsan.ghazanfari@uvm.edu	Environmental			
		Engineering			
		Electrical and	Co-Principal Investigator		
Hamid Ossareh	Hamid.Ossareh@uvm.edu	Biomedical			
		Engineering			

Table 6: Student Participants during the reporting period					
Student Name Email Address Class Major Role in research					
Maziar Foroutan		Ph.D.	Civil & Environmental Engineering	Graduate Research Assistant	
Ahmad Ghazanfari		M.S.	Electrical and Biomedical Engineering	Graduate Research Assistant	

Table 7: Student Graduates					
Student Name Role in Research Degree Graduation Date					
None					

Table 8: Research Project Collaborators during the reporting period						
		Contribution to the Project				
Organization	Location	Financial	In-Kind	Facilities	Collaborative	Personnel
		Support	Support	racinties	Research	Exchanges
None						

Table 9: Other Collaborators					
Collaborator Name and Title Contact Information Organization and Department Contribution to Research					
Title		Department	Researen		

Name: Callie Ewald

Title: Geotechnical Engineering Manager Organization: Vermont Agency of Transportation Location (City & State): Berlin, Vermont Email Address: callie.ewald@vermont.gov

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Changes:

None.

Planned Activities:

(i) analysis of the collected data from IC field tests aiming at IC performance improvement

(ii) continue improving the design and ruggedization of the passive sensors in IC compaction

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